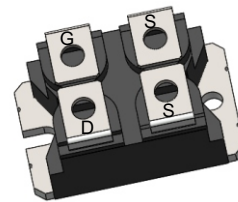


### Features

56N90S7P, the silicon N-channel Enhanced VDMOSFET, is obtained by the self-aligned planar Technology which reduce the conduction loss, improve switching performance and enhance the avalanche energy. The transistor can be used in various power switching circuit for system miniaturization and higher efficiency. The package form is SOT-227, which accords with the RoHS standard.

Product Summary			
V <sub>DS</sub>	R <sub>DS(on)</sub> (mΩ)Max	I <sub>D</sub> (A)	Q <sub>g</sub> (Max)
900V	145 @ 10V 22.5A	56	260nc

SOT-227



### Features

- Fast switching
- ESD Improved Capability
- Low Gate Charge
- Low Reverse transfer capacitances
- 100% Single Pulse avalanche energy Test

### Mechanical Data

- Case: SOT-227 Package

### Application

- Power switch circuit of POWER

### Block Diagram

Pin Definition:

- G. Gate
- D. Drain
- S. Source

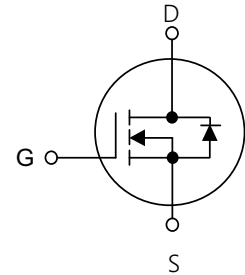


Table1 Absolute Maximum Ratings (T<sub>c</sub>=25°C, unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DS</sub>	900	V
Gate-Source Voltage	V <sub>GS</sub>	±40	V
Continuous Drain Current	I <sub>D</sub>	T <sub>c</sub> =25°C	56
		T <sub>c</sub> =100°C	30
Pulsed Drain Current (Note 1)	I <sub>DM</sub>	168	A
Power Dissipation T <sub>c</sub> =25°C	P <sub>D</sub>	700	W
Single Pulse Avalanche Energy(Note 2)	E <sub>AS</sub>	2500	mJ
Avalanche Current(Note 1)	I <sub>AR</sub>	20	A
Operating Junction and Storage Temperature	T <sub>J</sub> /T <sub>STG</sub>	-55~+150	°C

Table 2. Thermal Characteristics

Parameter	Symbol	SOT-227	Unit
Thermal resistance Case to heatsink	$R_{\theta CS}$	0.05	$^{\circ}C/W$
Thermal resistance Junction to Case	$R_{\theta JC}$	0.179	$^{\circ}C/W$

 Table 3. Electrical Characteristics ( $T_J=25^{\circ}C$ , unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	900	-	-	V
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=900V, V_{GS}=0V$	-	-	50	$\mu A$
Gate- Source Leakage Current	Forward	$I_{GSS}$	-	-	200	nA
	Reverse				-200	nA
On Characteristics						
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=8mA$	3.0	-	6.0	V
Static Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=22.5A$	-	-	145	m $\Omega$
Forward Trans conductance	$g_{fs}$	$V_{DS}=15V, I_D=22.5A$	-	30	-	S
Dynamic Characteristics						
Input Capacitance	$C_{ISS}$	$V_{DS}=25V, V_{GS}=0V, f=1MHz$	-	15	-	nF
Output Capacitance	$C_{OSS}$		-	1050	-	pF
Reverse Transfer Capacitance	$C_{RSS}$		-	120	-	pF
Switching Characteristics						
Turn-On Delay Time	$t_{d(on)}$	$V_{DD}=450V, I_D=20A$ $V_{GS}=10V, R_G=25\Omega,$	-	55	-	ns
Turn-On Rise Time	$t_r$		-	50	-	ns
Turn-Off Delay Time	$t_{d(off)}$		-	80	-	ns
Turn-Off Fall Time	$t_f$		-	45	-	ns
Total Gate Charge	$Q_G$	$V_{DD}=450V, I_D=22.5A,$ $V_{GS}=10V$	-	260	-	nC
Gate-Source Charge	$Q_{GS}$		-	80	-	nC
Gate-Drain Charge	$Q_{GD}$		-	120	-	nC
Drain-Source Diode Characteristics and Maximum Ratings(Note 3)						
Drain-Source Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_S=45A$	-	-	1.5	V
Maximum Continuous Drain-Source Diode Forward Current	$I_S$		-	-	56	A
Reverse Recovery Time	$t_{rr}$	$V_{GS}=0V, I_S=45A$ $di/dt=100A/\mu s$		500		ns
Reverse Recovery Charge	$Q_{RR}$			2.5		$\mu C$

Notes: 1 Repetitive Rating Pulse width limited by maximum junction temperature

2  $I_{SD}=56A, V_{DD} \leq BV_{DS}, di/dt \leq 100A/\mu s, \text{Starting } T_J=25^{\circ}C$

3 Pulse Test: Pulse width  $\leq 300\mu s, \text{Duty cycle} \leq 2\%$

Typical Characteristics Diagrams

Figure 1. Output Characteristics

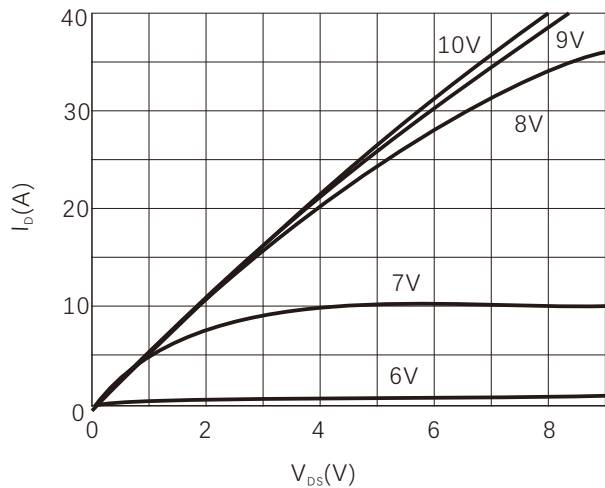


Figure 2. Normalized  $R_{DS(on)}$  vs Temperature

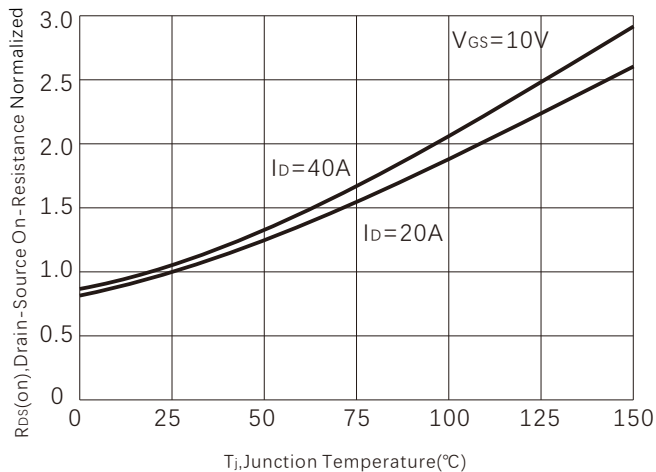


Figure 3. On-Resistance Normalized to  $I_D = 20A$  vs. Drain Current

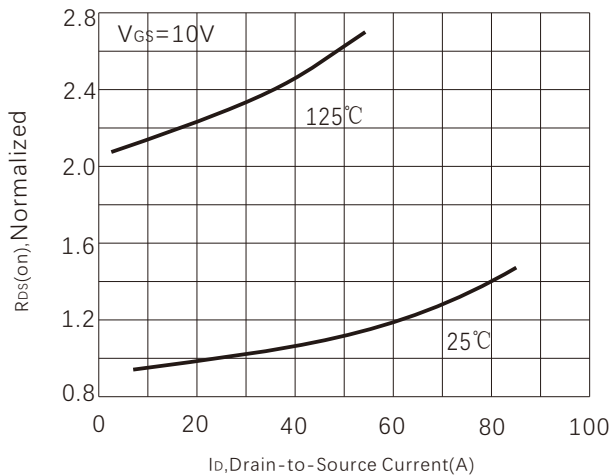


Figure 4. Capacitance

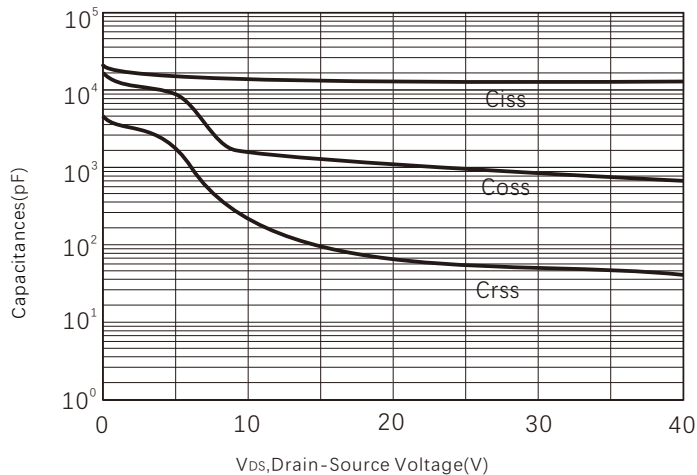


Figure 5. Gate charge

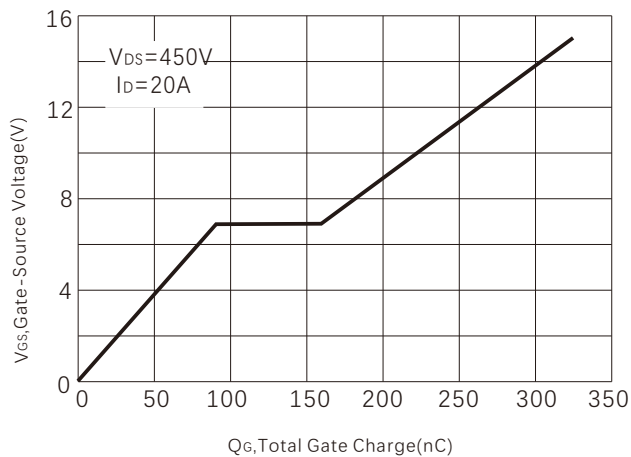


Figure 6. Source-Drain Diode Forward Voltage

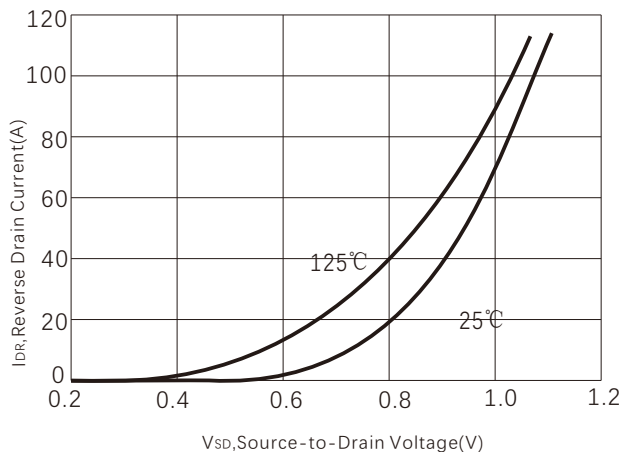


Figure 7. Maximum Drain Current vs Temperature

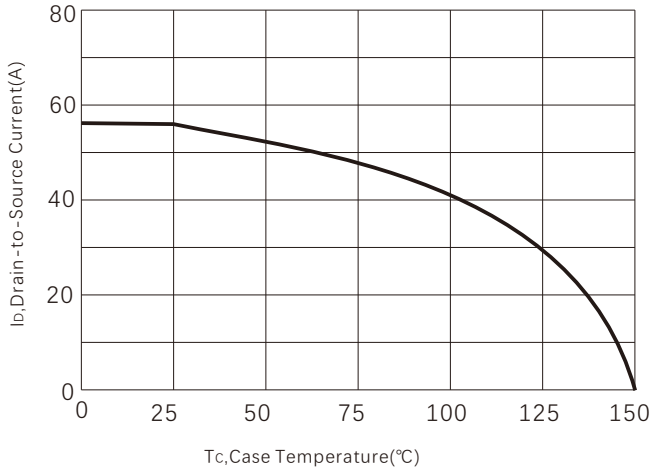


Figure 8. Transfer Characteristics

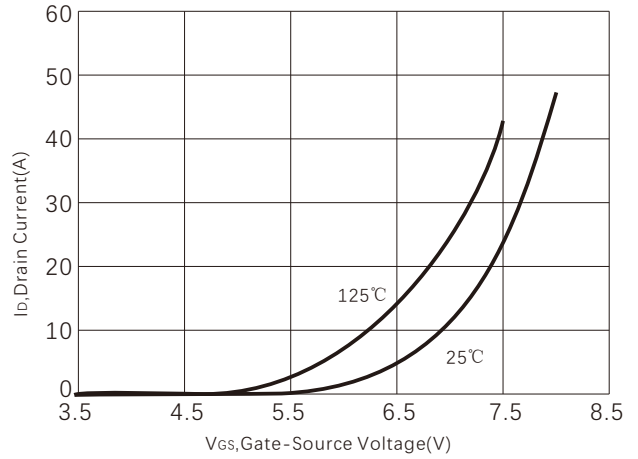


Figure 9. Safe operating area

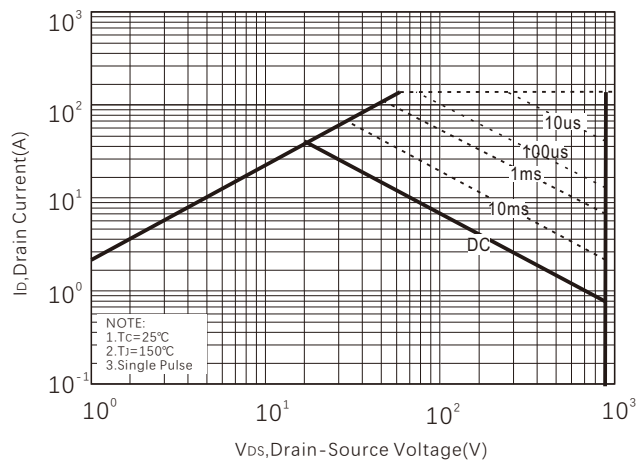
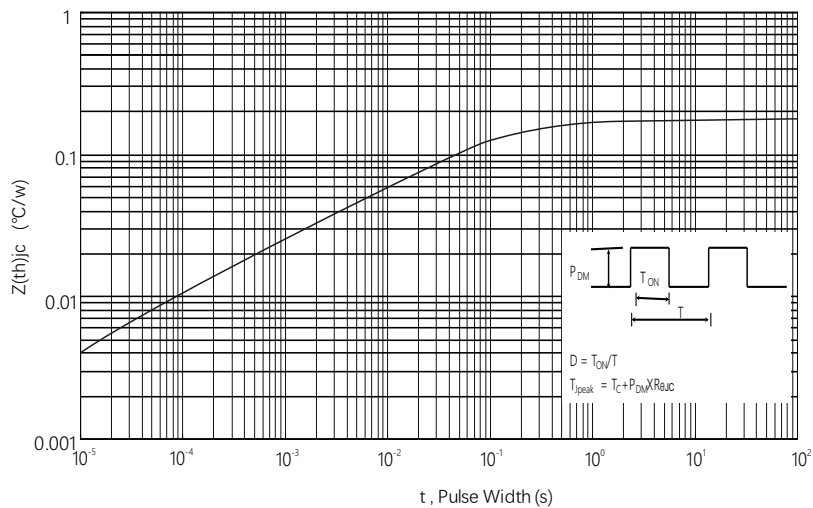
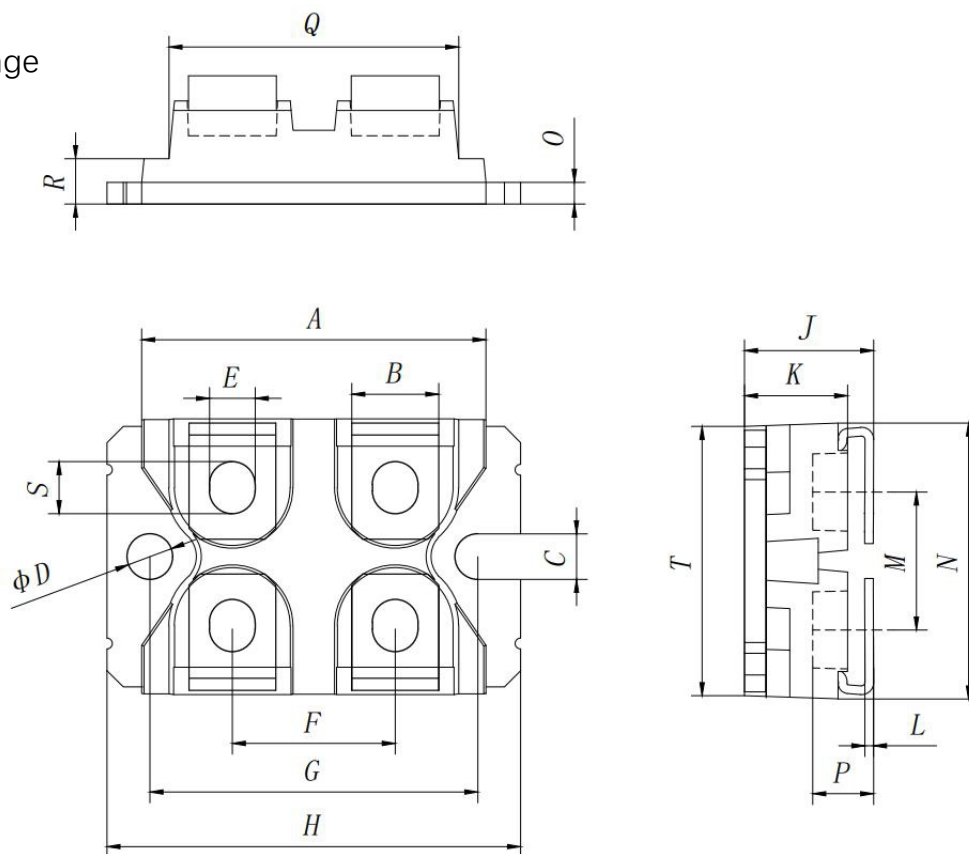


Figure 10. Maximum Transient Thermal Impedance



Dimensions

SOT-227package



SYMBOLS	DIMENSION IN MM		
	MIN	NOM	MAX
<i>A</i>	31.20	31.70	32.20
<i>B</i>	7.50	8.00	8.50
<i>C</i>	3.80	4.20	4.60
<i>D</i>	3.80	4.20	4.60
<i>E</i>	3.80	4.20	4.60
<i>F</i>	14.50	15.00	15.50
<i>G</i>	29.80	30.20	30.60
<i>H</i>	37.70	38.10	38.50
<i>J</i>	11.50	11.90	12.30
<i>K</i>	8.90	9.50	10.00
<i>L</i>	0.75	0.80	0.85
<i>M</i>	12.40	12.70	13.00
<i>N</i>	25.00	25.40	25.80
<i>O</i>	1.70	2.00	2.30
<i>P</i>	4.95	5.60	6.10
<i>Q</i>	26.40	26.70	27.00
<i>R</i>	3.90	4.18	4.45
<i>S</i>	4.20	4.80	5.40
<i>T</i>	23.80	24.80	25.80

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